

**EXPEDITED PROCEDURE**

**RESPONSE UNDER 37 CFR § 1.116--EXAMINING GROUP 2811**

**PATENT**

Certificate of Mailing/Transmission (37 C.F.R. § 1.8(a))	
I hereby certify that this correspondence is, on the date shown below, being:	
<input checked="" type="checkbox"/> <b>ELECTRONIC FILING</b> transmitted to the United States Patent and Trademark Office's EFS-Web System	<input type="checkbox"/> <b>FACSIMILE</b> transmitted by facsimile to the Patent and Trademark Office, (571) 273-8300
<u>8/9/2006</u> Date	<u>Arnette Dodge</u> Name of Person Certifying  <u>Arnette Dodge</u> Signature of Person Transmitting Paper and Fee

**In the United States Patent and Trademark Office**

**Date:** August 9, 2006

**In re Application of:** Gaynes et al.

**Filed:** 11/28/2003

**For:** Optimized Conductive Lid Mounting For Integrated Circuit Chip Carriers

**Serial Number:** 10/707,206

**Art Unit:** 2811

**Examiner:** Junghwa M. Im

**REPLY AND AMENDMENT AFTER FINAL REJECTION UNDER 37 C.F.R. '1.116**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is in response to the Final Office Action mailed on June 15, 2006, which is due for response by September 15, 2006. Any fees required in entering this response may be charged to Applicants' deposit account, 09-0456.

Applicants respectfully request reconsideration of the outstanding rejections and reexamination of the present application in light of the following remarks and amendments. No new matter has been included.

FR920030002US1  
SN 10/707,206